产品规格承认书

SPECIFICATIONS

	客户:							
	CUSTOMER: _							
	产品名称:							
	DESCRIPTION	•						
	客户型号:							
	CUSTOMER PA	DT No.			WIFI ANT			
		K1 NO						
	产品型号:							
	OUR MODEL N	0:		PE	X3216DA	<u>\01</u>		
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DOCUMENT

NO.

SPEC REV.

3216

TITLE: CHIP2450-3216 Specification

PBX3216DA01 Specification

Operating Temp. : -40 ℃~+85 ℃

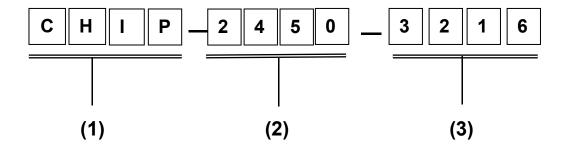
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

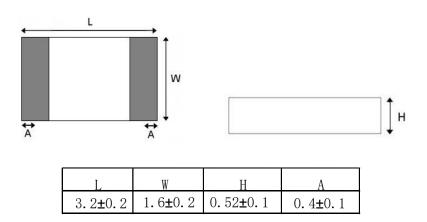
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION



- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 3.2*1.6

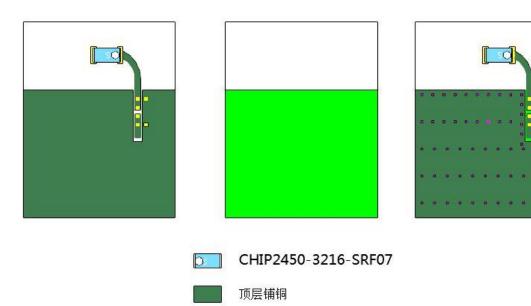
4. SHAPE AND DIMENSIONS:



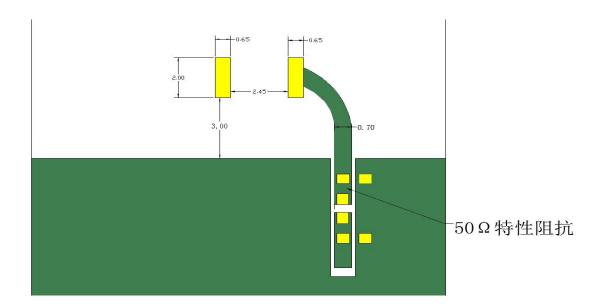
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测试板参考尺寸:

单位: mm

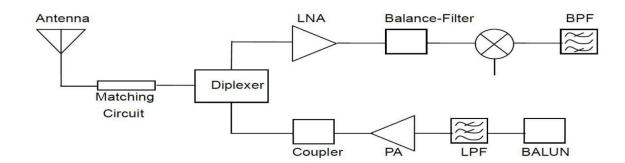






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APPLICATION GUIDE

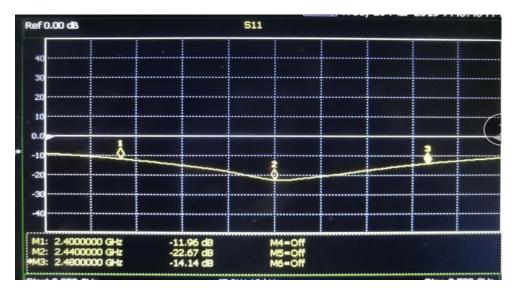


5. SPECIFICATIONS:

No.	Product number	PBX3216DA01	
1	Central Frequency	2440	MHz
2	Bandwidth	100 (Min.)	MHz
3	Return Loss	-11.96 (Max.)	dB
4	Peak Gain	2.73	dBi
5	Impedance	50	Ω
6	Operating Temperature	-40~+85	C
7	Maximum Power	5	w
8	Resistance to soldering heat	10 (@260℃)	Sec.
9	Polarization	Linear	,
10	Azimuth Beam width	Omni-directiona	I
11	Termination	Sn (leadless)	
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6. Electrical Characteristics:



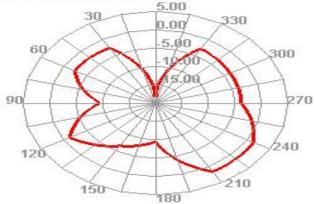


Frequency (MHz)	2400	2450	2500
Avg. Gain (dBi)	-1.83	-1.86	-2.97
Peck Gain (dBi)	2.7	2.58	1.34
Efficiency (%)	65.5	65.22	50.45

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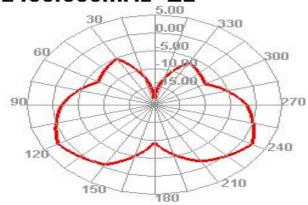
X-Y Plane



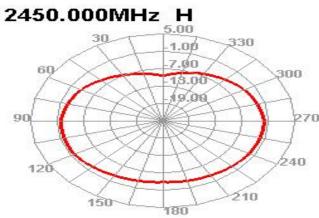


X-Y Plane

2450.000MHz E2

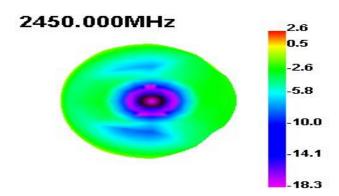


X-Y Plane



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3D Radiation Pattern



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7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at -40° C $\pm5^{\circ}$ C, 2. Convert to $+105^{\circ}$ C (5 minutes) 3. 30 ± 3 minutes at $+105^{\circ}$ C $\pm5^{\circ}$ C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm5^{\circ}$ C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : $260\pm5^{\circ}$ C 2. Bathing time: 10 ± 1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm5^\circ\!$	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

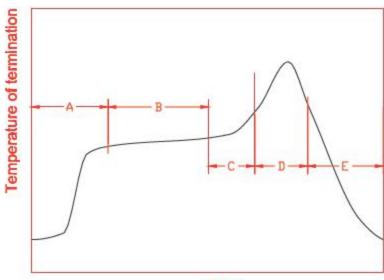
The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40° C to $+105^{\circ}$ C.

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8. Recommended Reflow Soldering



Time

1 st rising temperature	The normal to Preheating temperature	30s to 60s
Preheating	140°C to 160°C	60s to 120s
2 nd rising temperature	Preheating to 200°C	20s to 40s
	if 220°C	50s~60s
D Main heating	if 230°C	40s∼50s
	if 240°C	30s~40s
	if 250°C	20s~40s
	if 260°C	20s~40s
Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s
	Preheating 2 nd rising temperature Main heating	1st rising temperature Preheating 2nd rising temperature Preheating to 200°C if 220°C if 230°C Main heating if 240°C if 250°C if 260°C

^{*}reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- (a) The tip temperature must be less than $350^{\circ}\,$ C for the period within 3 seconds by using soldering gun under 30 W.
 - (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

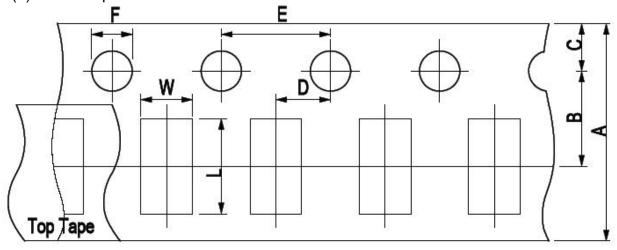
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TITLE: CHIF 2430-32 TO Specification		NO.	3210	P1		

Note that excess of soldering volume will easily get crack the body of this product.

9. Taping Package and Label Marking: (unit: mm)

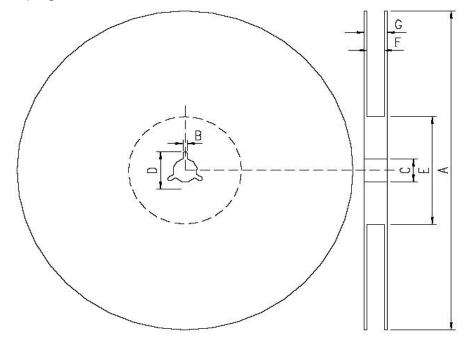
(1) Quantity/Reel: 5000pcs/Reel

(2) Carrier tape dimensions



Type	A	В	С	D	Е	F	L	W
2450-21	8.00 ± 0.3	3.50 ± 0.05	1.75±0.1	2.00 ± 0.05	4.00 ± 0.1	1.50 ± 0.1	2.30 ± 0.1	1.55 \pm 0.1

(3) Taping reel dimensions



A	178.0±2.0
В	2.0±0.5
С	13.0±0.5
D	21.0±0.8
Ε	62.0±1.5
F	9.0±0.5
G	13.0±1.0

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